

	Class	Number
ISSUE CLASSIFICATION		

PATIENT NUMBER

U.S. UTILITY Pat nt Application

MR J.P.E. SCANNED <u>IK4</u> Q.A. <u>Am</u>	PATENT DATE
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APPLICATION NO. 09/879556	CONT/PRIOR F	CLASS 257	SUBCLASS 773	ART UNIT 2811	EXAMINER <i>Thoma</i>
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APPLICANTS Jong-Hyun Ahn

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TITLE Metal interconnect layer of semiconductor device and method for forming a metal interconnect layer

PTO-2040
12/89

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____				ISSUE FEE	
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